Compliant with IEC 62474/ D9.00 Compliant to IEC 61249-2-21:2003

MICROCHIP Semiconductor Device Type: LT / LTY (8AX) 005 SC-70 NiPdAu			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)				JEDEC 97 Product Marking and/or Pkg. Labeling e4
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	mag	3.94	(mg) Total	Mold Compound	% ot Total Weight	62.53
Silica, vitreous	60676-86-0	Mold Compound	53.151	3,348	531.505		Silica, vitreous	60676-86-0	85.00	
Epoxy Resin	Trade Secret	Mold Compound	3.830	0.241	38,300		Epoxy Resin	Trade Secret	6.13	
Phenolic Resin	Trade Secret	Mold Compound	3.830	0.241	38,300		Phenolic Resin	Trade Secret	6.13	
Epoxy, Cresol Novolac	29690-82-2	Mold Compound	1.532	0.097	15,320		Epoxy, Cresol Novolac	29690-82-2	2.45	
Carbon Black	1333-86-4	Mold Compound	0.188	0.012	1,876		Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Lead Frame	24.821	1.564	248,212			Total	100.00	_
Iron	7439-89-6	Lead Frame	0.587	0.037	5,867	1.61	(mg) Total	Lead Frame	% of Total Weight	25.51
Phosphorous	7723-14-0	Lead Frame	0.064	0.004	638		Copper	7440-50-8	97.30	
Zinc (Metal)	7440-66-0	Lead Frame	0.038	0.002	383		Iron	7439-89-6	2.30	
Aluminum oxide	1344-28-1	Die Attach	0.601	0.038	6,012		Phosphorous	7723-14-0	0.25	
Diethylene glycol monoethyl ether acetate	112-15-2	Die Attach	0.601	0.038	6,012		Zinc (Metal)	7440-66-0	0.15	
Epoxy resin	Trade Secret - 10114	Die Attach	0.328	0.021	3,279			Total		_
Epoxy resin	Trade Secret - 10105	Die Attach	0.164	0.010	1,640	0.11	(mg) Total	Die Attach	% of Total Weight	1.76
Amine	Trade Secret - 10039	Die Attach	0.066	0.004	656		Aluminum oxide	1344-28-1	34.16	
Silicon	7440-21-3	Chip (Die)	7.520	0.474	75,200	Diethylene gly	ycol monoethyl ether acetate	112-15-2	34.16	1
Gold	7440-57-5	Wire Bond	1.430	0.090	14,300		Epoxy resin	Trade Secret - 10114	18.63	
Nickel	7440-02-0	Plating on external leads (pins)	1.125	0.071	11,250		Epoxy resin	Trade Secret - 10105	9.32	
Palladium	5/3/7440	Plating on external leads (pins)	0.063	0.004	625		Amine	Trade Secret - 10039	3.73	
	7440-57-5	Plating on external leads (pins)	0.063	0.004	625			Total	100.00	=
Gold	7440-57-5									
Gold	7440-57-5	TOTA	S: 100.000	6.300	1,000,000	0.47	Total (mg)	Chip (Die)	% of Total Weight	7.52
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